

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1.-37. (Canceled)

38. (Currently Amended) A semiconductor device, comprising:  
a substrate having contact pads exposed at a surface thereof, the contact pads being arranged in at least one substantially linear relationship positioned at or proximate a centerline of the substrate and being configured to communicate with corresponding test pads of a test substrate upon disposing the substrate face-down over the test substrate; and  
at least one stabilizer protruding from the surface, the at least one stabilizer being configured to at least partially stabilize an orientation of the semiconductor device upon disposal thereof face-down over the test substrate and including a plurality of ~~superimposed, contiguousadjacent~~, mutually adhered ~~layers~~ regions of the same material.

39. (Previously Presented) The semiconductor device of claim 38, wherein the at least one stabilizer protrudes from the surface at most a distance between a plane of the surface of the substrate and a plane of a surface of the test substrate upon disposing the substrate face-down over the test substrate.

40. (Previously Presented) The semiconductor device of claim 39, wherein the at least one stabilizer protrudes from the surface at most the distance between the plane of the surface of the substrate and the plane of the surface of the test substrate when at least one conductor connects at least one of the contact pads and a corresponding one of the test pads.

41. (Previously Presented) The semiconductor device of claim 38, wherein the at least one stabilizer comprises a dielectric material.

42. (Previously Presented) The semiconductor device of claim 38, wherein the at least one stabilizer comprises a photopolymer.

43. (Previously Presented) The semiconductor device of claim 42, wherein the photopolymer is at least semisolid.

44. (Canceled)

45. (Previously Presented) The semiconductor device of claim 38, wherein the at least one stabilizer is positioned to be located proximate a corner of the surface.

46. (Previously Presented) The semiconductor device of claim 38, wherein the at least one stabilizer is positioned to be located proximate an edge of the surface.

47. (Previously Presented) The semiconductor device of claim 38, wherein the at least one stabilizer has a cross-sectional plan of one of quadrilateral, round, oval, and triangular.

48. (Previously presented) The semiconductor device of claim 38, wherein the at least one stabilizer is elongated in a direction parallel to a plane in which the substrate is located.

49. (Previously Presented) The semiconductor device of claim 38, wherein the substrate comprises a semiconductor wafer.

50. (Previously Presented) The semiconductor device of claim 38, wherein the substrate comprises a semiconductor die.

51. (Previously Presented) The semiconductor device of claim 38, wherein the substrate comprises a chip-scale package.

52. (Previously Presented) The semiconductor device of claim 38, wherein the test substrate also includes at least one stabilizer configured to at least partially stabilize the substrate upon disposing the substrate face-down over the test substrate.

53. (Currently Amended) A test substrate, comprising:  
a substrate having test pads exposed at a surface thereof, the test pads being arranged in at least one substantially linear relationship and configured to temporarily communicate with corresponding contact pads which are arranged in at least one substantially linear relationship which is positioned at or proximate a centerline of a semiconductor device to be disposed face-down over the substrate; and  
at least one stabilizer protruding from the surface, the at least one stabilizer being configured to at least partially stabilize the semiconductor device upon disposal thereof face-down over the test substrate.

54. (Previously Presented) The test substrate of claim 53, wherein the at least one stabilizer protrudes from the surface at most a distance between a plane of the surface of the substrate and a plane of a surface of the semiconductor device upon disposing the semiconductor device face-down over the substrate.

55. (Previously Presented) The test substrate of claim 54, wherein the at least one stabilizer protrudes from the surface at most the distance between the plane of the surface of the substrate and the plane of the surface of the semiconductor device when at least one conductor connects at least one of the contact pads and a corresponding one of the test pads.

56. (Previously Presented) The test substrate of claim 53, wherein the at least one stabilizer comprises a photopolymer.

57. (Previously Presented) The test substrate of claim 56, wherein the photopolymer is at least semisolid.

58. (Currently Amended) The test substrate of claim 56, wherein the at least one stabilizer comprises a plurality of ~~superimposed, contiguous adjacent~~, mutually adhered ~~layers~~regions.

59. (Previously Presented) The test substrate of claim 53, wherein the semiconductor device has at least one stabilizer secured to a surface thereof, the at least one stabilizer configured to at least partially stabilize the semiconductor device upon disposal of the semiconductor device face-down over the substrate.

60. (Previously Presented) An assembly of a semiconductor device and a test substrate, comprising:

a test substrate with a plurality of test pads exposed at a surface thereof and arranged in at least one substantially linear relationship;

a semiconductor device with a plurality of contact pads exposed at a surface thereof, the plurality of contact pads being arranged in at least one substantially linear relationship which is located at or proximate a centerline of the semiconductor device, the surface of the semiconductor device facing the surface of the test substrate with the plurality of contact pads in temporary communication with corresponding test pads of the plurality of test pads; and

at least one stabilizer disposed between the test substrate and the semiconductor device.

61. (Previously Presented) The assembly of claim 60, wherein the at least one stabilizer is secured to the surface of the test substrate.

62. (Previously Presented) The assembly of claim 60, wherein the at least one stabilizer is secured to the surface of the semiconductor device.

63. (Previously Presented) The assembly of claim 60, comprising a plurality of stabilizers, at least one of the plurality of stabilizers being secured to the surface of the test substrate and at least one other of the plurality of stabilizers being secured to the surface of the semiconductor device.

64. (Previously Presented) The assembly of claim 60, wherein the at least one stabilizer comprises a photopolymer.

65. (Previously Presented) The assembly of claim 60, wherein the photopolymer is at least semisolid.

66. (Currently Amended) The assembly of claim 64, wherein the at least one stabilizer has a plurality of ~~superimposed, contiguous~~adjacent, mutually adhered ~~layers~~regions.

67. (Previously Presented) The assembly of claim 60, wherein the at least one stabilizer extends between a plane of the surface of the test substrate and a plane of the surface of the semiconductor device at most a distance between the planes of the surfaces upon establishing communication between the plurality of contact pads and the corresponding test pads.

68. (Previously Presented) The assembly of claim 60, further comprising at least one conductive structure disposed between the test substrate and the semiconductor device.

69. (Previously Presented) The assembly of claim 68, wherein the at least one stabilizer extends between a plane of the surface of the test substrate and a plane of the surface of the semiconductor device at most a distance the at least one conductive structure extends between the planes of the surfaces.

70-74 (Canceled)